

[54] SEMICONDUCTOR ELEMENT

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[**] Term: 14 Years
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[58] Field of Search D13/12, 20, 99;
361/401, 403, 404, 405; 357/70, 72, 74, 80;
174/52.4; 437/209

[56] References Cited
U.S. PATENT DOCUMENTS
3,833,753 9/1974 Garboushian 174/52.4 X
3,846,734 11/1974 Pauza et al. 361/403 X
4,663,833 5/1987 Tanaka et al. 437/209

FOREIGN PATENT DOCUMENTS

0235503 9/1987 European Pat. Off. 357/74
0197839 12/1982 Japan 357/72
0219949 12/1984 Japan 357/72
0217651 10/1985 Japan 357/74
0172352 8/1986 Japan 357/74

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[57] CLAIM

The ornamental design for a semiconductor element, as shown and described.

DESCRIPTION

FIG. 1 is a front elevational view of a semiconductor element showing my new design;
FIG. 2 is a rear elevational view thereof;
FIG. 3 is a top plan view thereof;
FIG. 4 is a bottom plan view thereof; and
FIG. 5 is a left side elevational view thereof, the right side elevational view being the same.

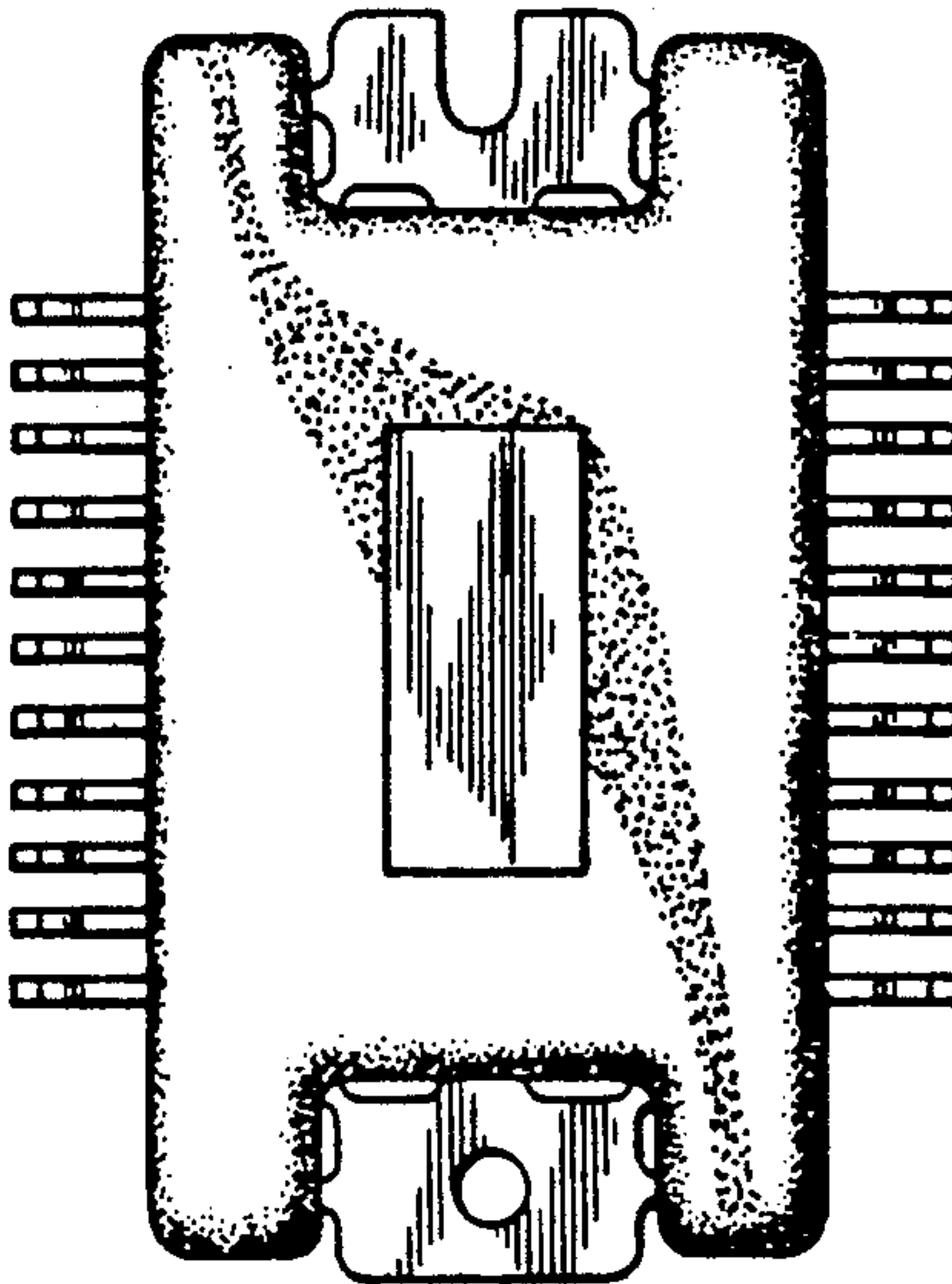


FIG. 1



FIG. 2



FIG. 3

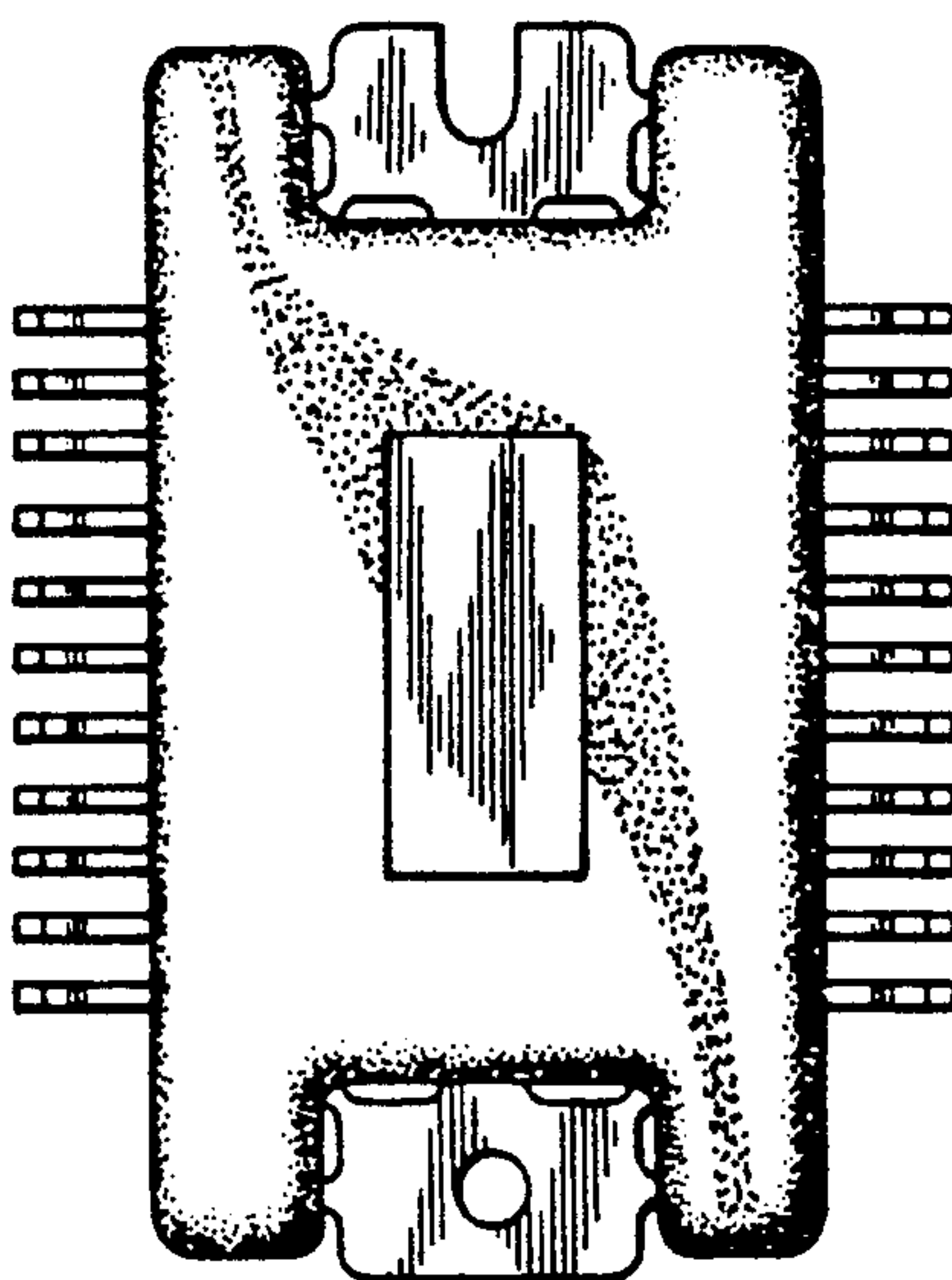


FIG. 4

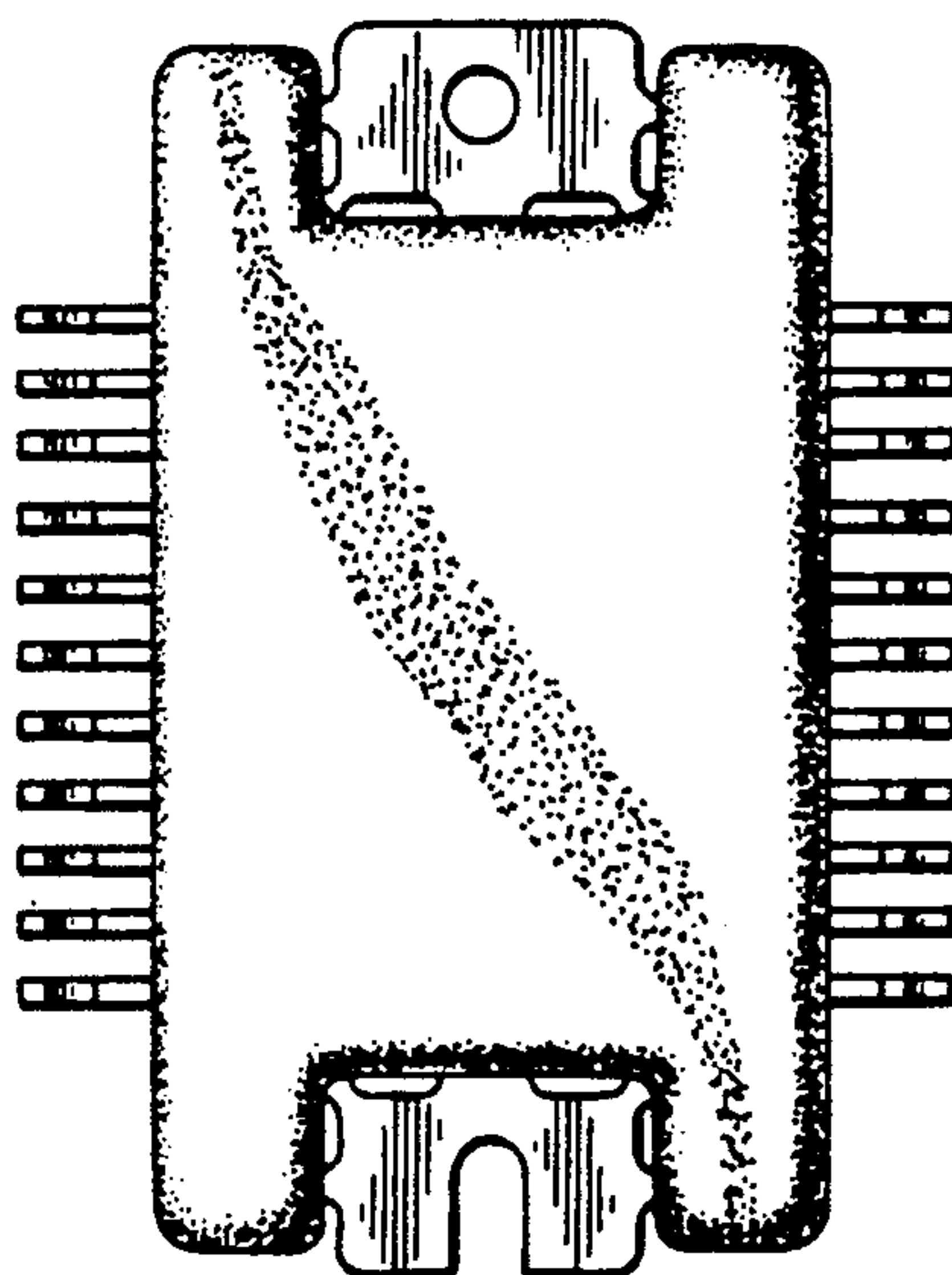


FIG. 5

